

NOTES:

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE:
 B/F NO.1,11,22,32,43,53,64,74-----300m OHM MAX.
 THE OTHERS-----600m OHM MAX.

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						85 PIN GRID ARRAY PACKAGE	UNLESS OTHERWISE SPECIFIED	S.N	T.A		JAN.16.'85
						SCALE 5/1	MATERIAL AS INDICATED				
							$\pm .005$				
	REDRAWN (CONVERTED TO CAD DATA)	DEC.05.'95	K.IM	H.S/K.M	T.A	KYOCERA	THIRD ANGLE PROJECTION	DRAWING NO.			SHEET
	CHANGED	DATE	DRAWN	CHECKED	APPROVED			KYOCERA CORPORATION KYOTO JAPAN	KD-P85033-A		1/3

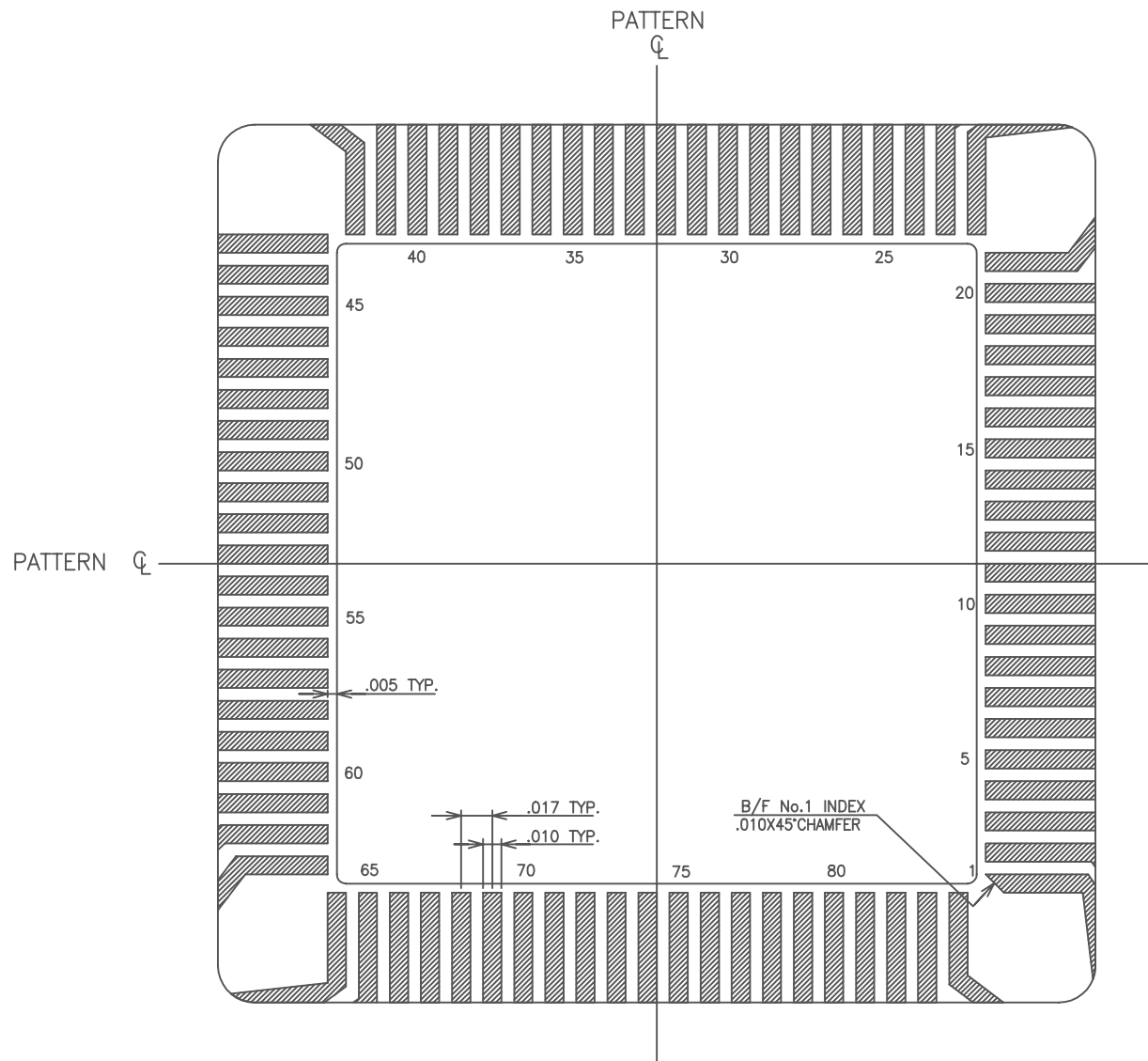
PB085R033-1 S=0 D=0

DRAWN | CHECKED | APPROVED | DATE

S.N T.A

DRAWING NO. SHEET

KD-P85033-A 1/3



BONDING PATTERN

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						85 PIN GRID ARRAY PACKAGE	UNLESS OTHERWISE SPECIFIED	W.M	T.A		JAN.22'85
						SCALE 20/1					
						MATERIAL					
							THIRD ANGLE PROJECTION				
	△ REDRAWN (CONVERTED TO CAD DATA)	DEC.05'95	K.IM	H.S/K.M	T.A		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.		SHEET 2/3	
	CHANGED	DATE	DRAWN	CHECKED	APPROVED			KD-P85033-A			

WIRE BOND PAD / CONNECTOR PIN INTERCONNECTION PLAN

W/B NO.	PIN NO.
1	B 2
2	C 2
3	B 1
4	C 1
5	D 2
6	D 1
7	E 3
8	E 2
9	E 1
10	F 2
11	F 3
12	G 3
13	G 1
14	G 2
15	F 1
16	H 1
17	H 2
18	J 1
19	K 1
20	J 2


W/B NO.	PIN NO.
21	L 1
22	K 2
23	K 3
24	L 2
25	L 3
26	K 4
27	L 4
28	J 5
29	K 5
30	L 5
31	K 6
32	J 6
33	J 7
34	L 7
35	K 7
36	L 6
37	L 8
38	K 8
39	L 9
40	L10

W/B NO.	PIN NO.
41	K 9
42	L11
43	K10
44	J10
45	K11
46	J11
47	H10
48	H11
49	F10
50	G10
51	G11
52	G 9
53	F 9
54	F11
55	E11
56	E10
57	E 9
58	D11
59	D10
60	C11

W/B NO.	PIN NO.
61	B11
62	C10
63	A11
64	B10
65	B 9
66	A10
67	A 9
68	B 8
69	A 8
70	B 6
71	B 7
72	A 7
73	C 7
74	C 6
75	A 6
76	A 5
77	B 5
78	C 5
79	A 4
80	B 4

W/B NO.	PIN NO.
81	A 3
82	A 2
83	B 3
84	A 1

S/R	N C
D/A	N C
EXTRA PIN (C3)	C 2

MODIFICATION							NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
							85 PIN GRID ARRAY PACKAGE	UNLESS OTHERWISE SPECIFIED	W.M	T.A		JAN.16.'85
							SCALE \times	MATERIAL				
								THIRD ANGLE PROJECTION				
	A REDRAWN (CONVERTED TO CAD DATA)	DEC.05.'95	K.IM	H.S/K.M	T.A		 KYOCERA CORPORATION KYOTO JAPAN		DRAWING NO.			SHEET
	CHANGED	DATE	DRAWN	CHECKED	APPROVED			KD-P85033-A	3		3	